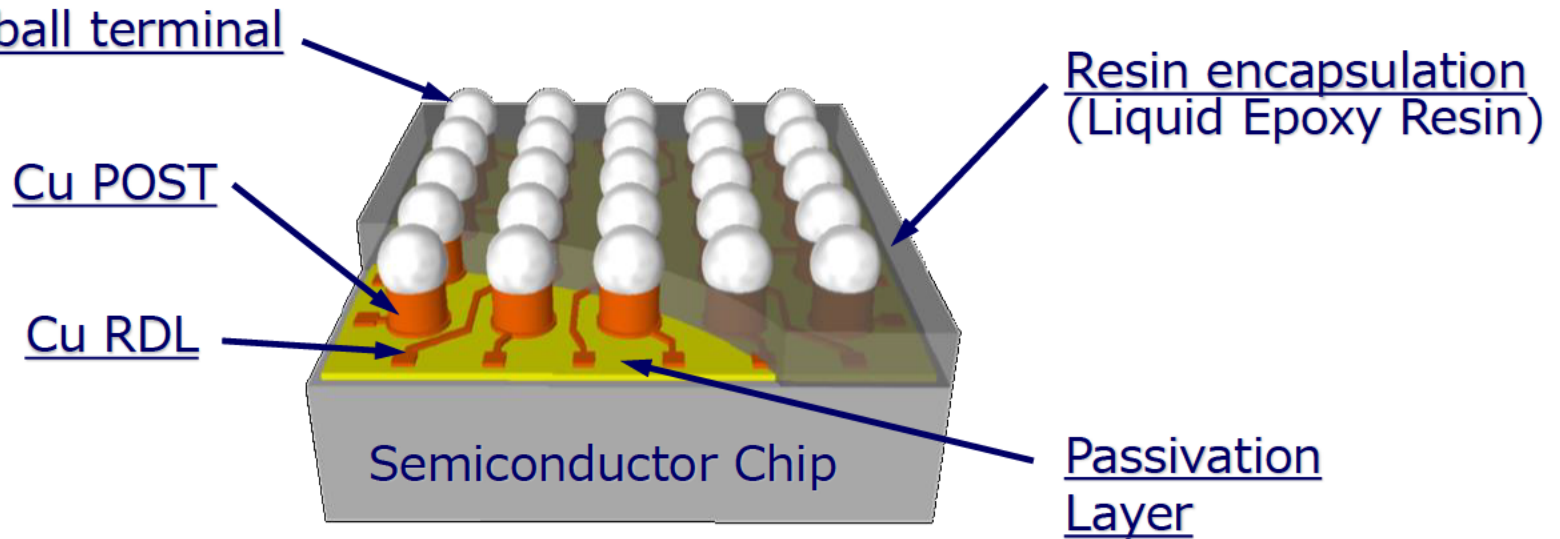


# WLP

( Wafer Level Package )

## Cu POST Type WLP Construction and Characteristic



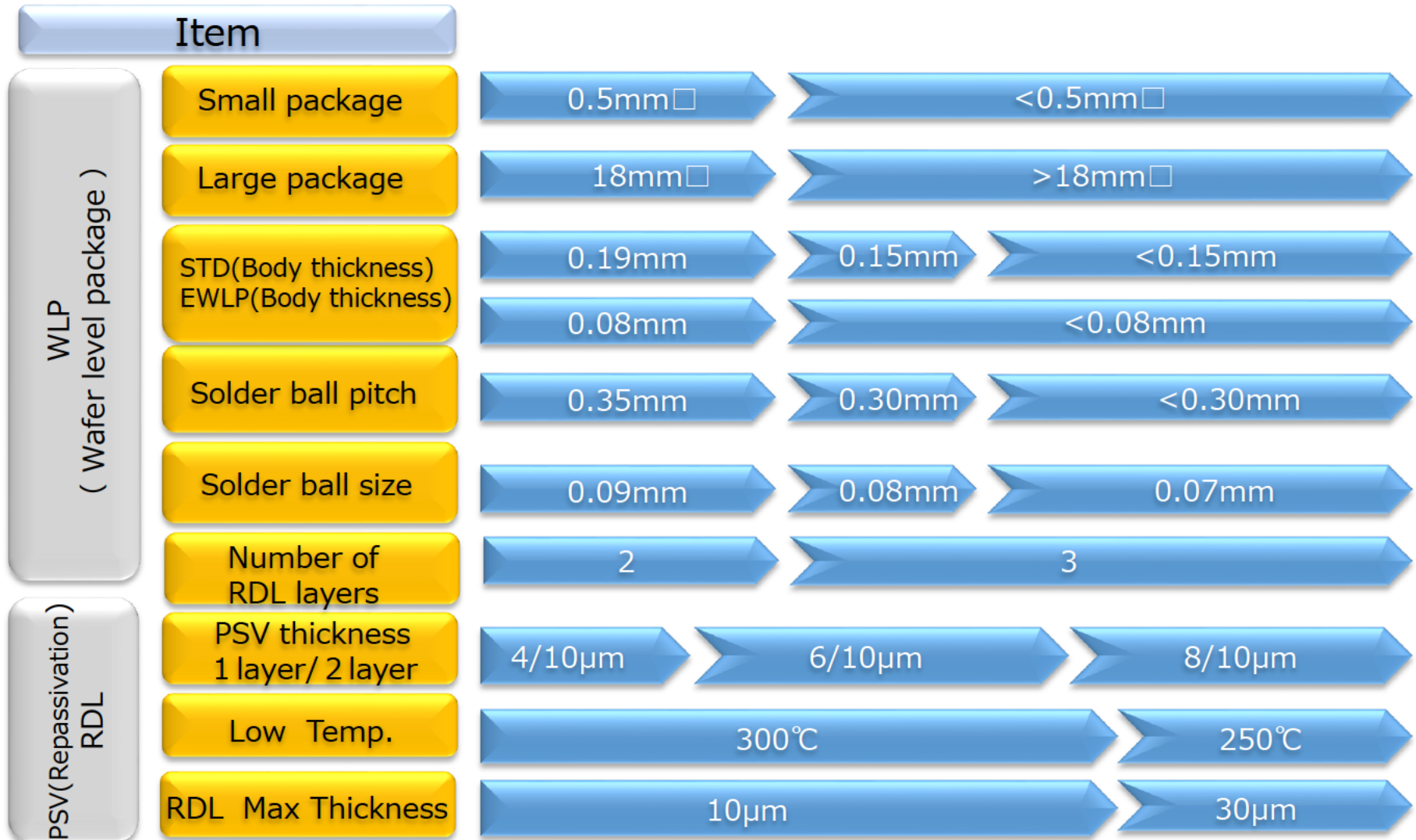
### Characteristic (Summary)

- ① High reliability/High electrical characteristics.
- ② High current capacity
- ③ Reduce chipping on Circuit side (Protected by resin)
- ④ Improve quality for low-k
- ⑤ Improve mountability (High precision coplanarity)
- ⑥ Low temperature process  
(Damage reduction for insulation film)

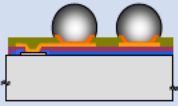
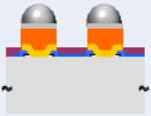
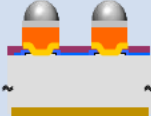

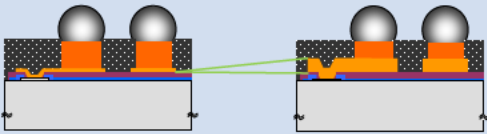
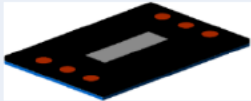
## Package Lineup

|                 | WLP                                      |          | Bump   |            |             |
|-----------------|--|----------|--|------------|-------------|
|                 | CP-Type                                  | U-Type   | Cu-Pillar                                      | Micro Bump | Solder ball |
| Wafer size      | 12,8,6                                   | 12,8,(6) | 12,8,(6)                                       | 12,8,(6)   | 12,8,6,(4)  |
| Current         | 5A                                       | 1A       |  |            |             |
| Min. pitch (um) | 350                                      | 150      | 40   | 40         | 150         |
| Chip size (mm)  | 0.5 ~ 18                                 | 0.5 ~ 20 | 0.5 ~ 12                                       | 0.5 ~ 24   | 0.5 ~ 24    |
| Tooling needs   | 4 layers                                 | 5 layers | 2 layers                                       | 1 layer    | 3 layers    |
| Production      | ◎  | ○        | ○  | ○          | ◎           |
|                 | OEL original WLP and various WLP line up |          | Various Bump line up with customer requirement |            |             |

## Technology Roadmap



## Under Development (2020FY~)

| No. | ITEM                        | Structure   | Function   |
|-----|-----------------------------|---|--|
| 1   | Low temp. UBM-Type WLP      |    | Improving IC electrical characteristics.<br>250 degrees or less  |
| 2   | 8inch & 12inch WF Cu Pillar |    | Flip chip bonding for FOLP (Fan Out WLP).  |
| 3   | Back Side Metal             |    | Back Side Metal processing after WLP<br>Heat dissipation, electrical resistance reduction  |
| 4   | Non-Electrical Au Plating   |    | Gold wire can be made after RDL  |
| 5   | High current WLP            |   | By using our resin WLP, we are able to make thicker RDL, for large current product, which is difficult for other companies.<br>It will be advantage to make devices and for energy saving. |
| 6   | 2 in 1 WLP                  |  | Create 2in1 with WLP and fit in the chip size<br>Applications are MOS-FET etc.   |

## **ATTENTION**

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